ELITE SERIES
DRY-MATE CONNECTOR

HSC HERMETIC SEAL™ / AMETEK® ENGINEERED INTERCONNECT AND PACKAGING

General Description and Advantages

- Design Life 25 Years
- ISO/API Compliant Design
- 316SS Standard, Ti Gr 2, 5 Available
- Dual O-ring Seals at All Points of Seawater Entry
- O-rings Captured for Retention
- Fully Modular Design
- 19 Positions for Electrical or Optic Contacts
- Industry Standard Shell Sizes
- APC Contacts Available for Fiber Optic Version
- Permits Very High Back Refl ection Performance
- Cable Termination or PBOF Designs Available
- Glass Sealed Electrical Version Available



Design Parameters	Specification	
	Electrical	Fiber Optic
Material Specification, BCR or FCR	316SS nominal, Ti Available	
Material Specification, CCP	316SS nominal, Ti Available	
Design Life	25 Years	
Number of Circuits	1-19E	1-19FO
Design Water Depth	3000m	
Test Pressure	4500m	
Environmental Operating Temp in air/water	-5 C to +40 C	
Equipment Storage Temperature	-25 C to +50 C	
Mate/Demate Cycles	250 in spec, 1000 durability	
Max voltage - Mated and Unmated	1500VDC/1000VAC	
Insulation Resistance	> 20gohm at 1000 VDC	
Rated Current (16 awg)	13 amps	
Contact Size, nominal	16AWG	
Insertion Loss (IL) (UPC)		Less than 0.5dB @ 1310/1550nm
Back Refl ection (BR) (UPC/APC)		Greater than -35dB @ 1310/1550nm UPC (Greater than -45dB APC)

HSC HERMETIC SEAL™ / AMETEK® ENGINEERED INTERCONNECT AND PACKAGING

E: hermeticseal.info@ametek.com | **T:** +1 626 443 8931

www.hermeticseal.com

Scan for more information